

• General Description

The AGM1075MNA combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{\text{DS(ON)}}$

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- Low Gate Charge for fast switching
- ■Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

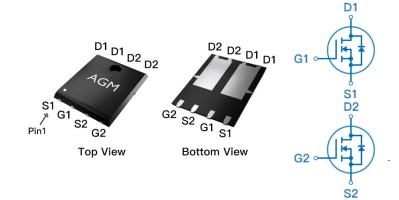
Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
100V	65mΩ	16A

PDFN5*6 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM1075MNA	AGM1075MNA	PDFN5*6	330mm	12mm	3000

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	100	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) (Note 1)	16	А
ID	Drain Current-Continuous(Tc=100℃)	10	А
IDM (pluse)	Drain Current-Pulsed (Note 2)	64	А
	Maximum Power Dissipation(Tc=25℃)	35	W
PD	Maximum Power Dissipation(Tc=100℃)	13	w
EAS	Avalanche energy (Note 3)	9	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$ C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹		20	°C/W
RθJC	Thermal Resistance Junction-Case ¹		3.6	°C/W



Table 3. Electrical Characteristics (TJ=25 ℃ unless otherwise noted)

Table 3. Electrical Characteristics (TJ=25 ℃ unless otherwise noted)					
Parameter	Conditions	Min	Тур	Max	Unit
tates					
Drain-Source Breakdown Voltage	VGS=0V ID=250μA	100	-		V
Zero Gate Voltage Drain Current	VDS=100V,VGS=0V			1	μΑ
Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
Gate Threshold Voltage	VDS=VGS,ID=250μA	1.2	1.7	2.2	V
Forward Transconductance	VDS=5V,ID=3A		5		S
Drain-Source On-State Resistance	VGS=10V, ID=10A		65	90	mΩ
	VGS=4.5V, ID=3A		99	130	mΩ
Characteristics					
Input Capacitance			205		pF
Output Capacitance	· ·		65		pF
Reverse Transfer Capacitance	, <u>-</u>		2.4		pF
Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		7.7		Ω
g Times					
Turn-on Delay Time			16.2		nS
Turn-on Rise Time	VGS=10V,VDS=50V,		3.2		nS
Turn-Off Delay Time	ID=10A,RGEN=6Ω		13		nS
Turn-Off Fall Time			22		nS
Total Gate Charge			6		nC
Gate-Source Charge	VGS=10V, VDS=50V ID=12A		1.1		nC
Gate-Drain Charge	- 100 001, 10 12/1		1.3		nC
Prain Diode Characteristics					
Source-Drain Current(Body Diode)				16	А
Forward on Voltage	VGS=0V,IS=10A			1.0	V
Reverse Recovery Time	Isd=10A ,		45		ns
Reverse Recovery Charge	dI/dt=100A/μs , TJ=25℃		63		nc
	Parameter ates Drain-Source Breakdown Voltage Zero Gate Voltage Drain Current Gate-Body Leakage Current Gate Threshold Voltage Forward Transconductance Drain-Source On-State Resistance Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate resistance Turn-on Delay Time Turn-on Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge rain Diode Characteristics Source-Drain Current(Body Diode) Forward on Voltage Reverse Recovery Time	Parameter Conditions	Parameter Conditions Min ates	Parameter Conditions Min Typ ates	Parameter Conditions Min Typ Max

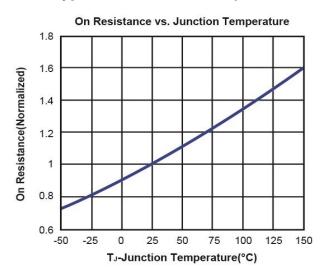
Notes 1. The maximum current rating is package limited.

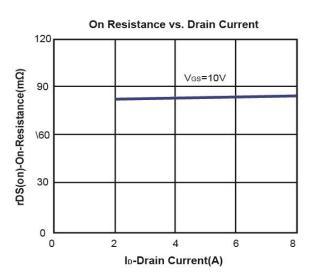
Notes 2. Repetitive Rating: Pulse width limited by maximum junction temperature

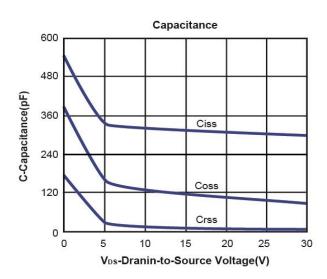
Notes 3.EAS condition: TJ=25 $^{\circ}$ C , VDD=50V,Vgs=10V,ID=6A,L=0.5mH,RG=25ohm

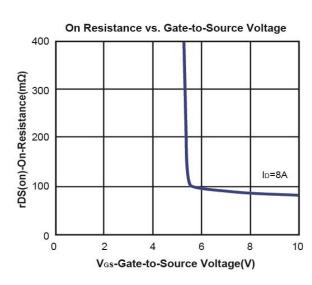


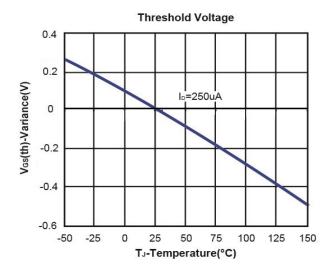
Typical Characteristics (TJ =25°C Noted)

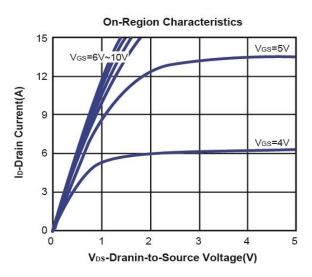






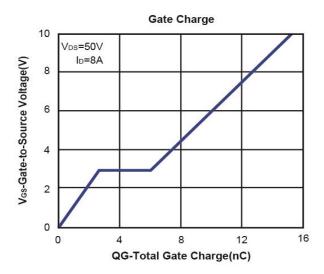


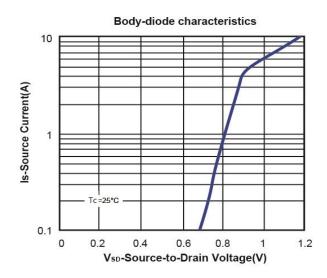


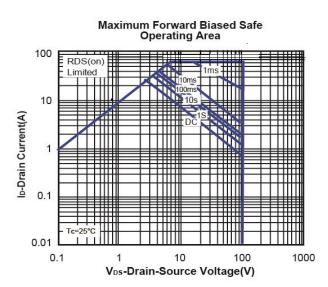


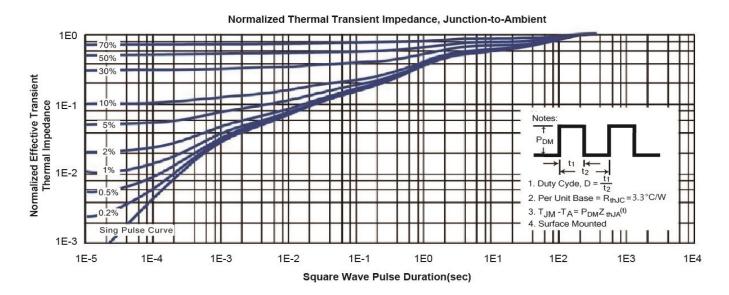


Typical Characteristics (TJ =25°C Noted)



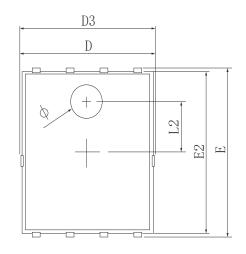


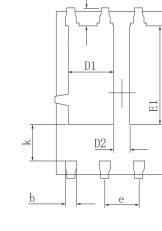




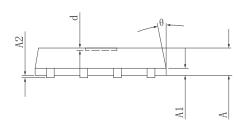


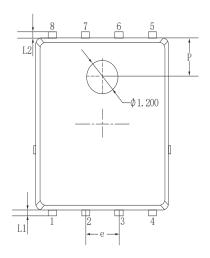
•Dimensions (PDFN5*6)

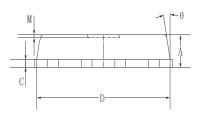


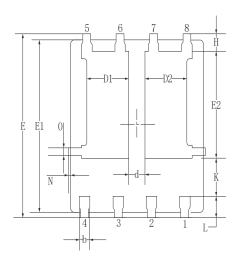


SYMBOL		MILLIMETER	}	
SIMDUL	MIN	Тур.	MAX	
A	0.900	1.000	1.100	
A1	0. 254 REF.			
A2		0~0.05		
D	4.824	4.900	4. 976	
D1	1.605	1. 705	1.805	
D2	0.500	0.600	0.700	
D3	4.924	5.000	5. 076	
Е	5. 924	6.000	6.076	
E1	3. 375	3. 475	3. 575	
E2	5. 674	5. 750	5.826	
b	0.350	0.400	0.450	
е	1.270 TYP.			
L	0. 534	0.610	0.686	
L1	0. 424	0.500	0.576	
L2	1.800 REF.			
k	1. 190	1. 290	1.390	
Н	0.549	0.625	0.701	
θ	8°	10°	12°	
Φ	1.100	1. 200	1.300	
d			0.100	







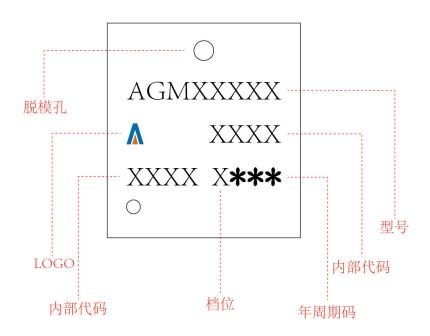


Symbol	Millitmeters		
эуш001	MIN.	NOM.	MAX.
A	0. 90	1.05	1. 20
b	0.35	0.40	0.50
С	0.20	0.25	0.35
D	4. 90	5. 05	5. 20
D1/D2	1.51	1.61	1.71
d	0.50	0.60	0.70
Е	6.00	6. 15	6.30
E1	5. 60	5. 75	5. 90
E2	3. 47	3. 57	3. 67
е		1. 27 BSC.	
Н	0.48	0. 58	0.68
K	1. 17	1. 27	1. 37
L	0.64	0.74	0.84
L1/L2	0.20 REF.		
θ	8°	10°	12°
M	0.08 REF.		
N	0	-	0.15
0	0.25 REF.		
Р	1.28 REF.		

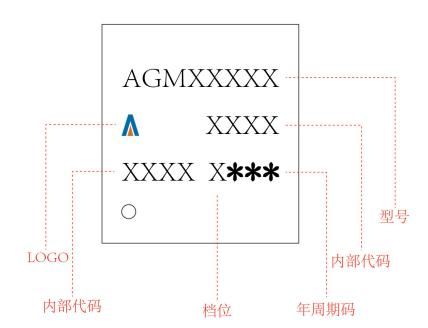


PDFN5*6 Marking Instructions:

Model1:



Model2:





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